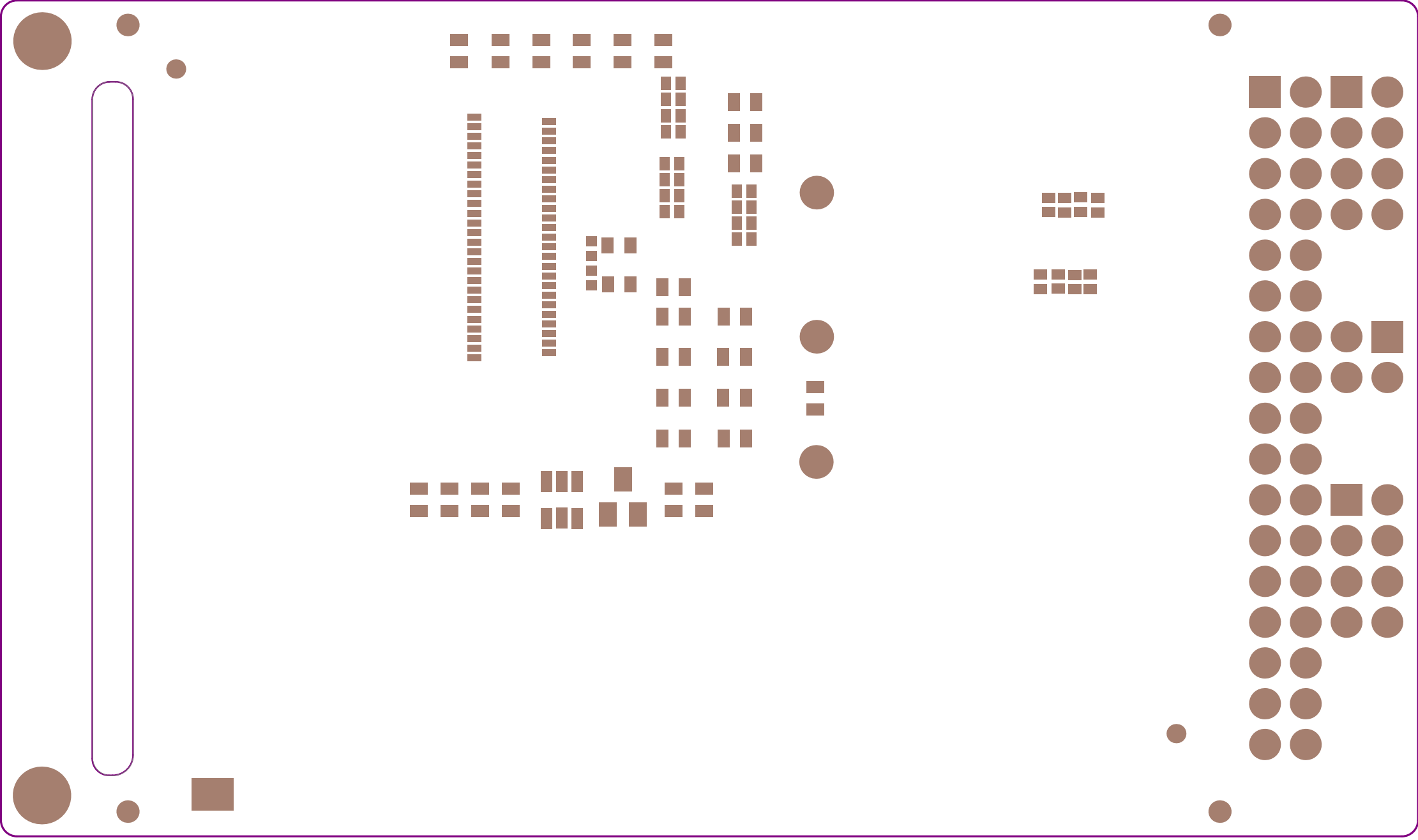
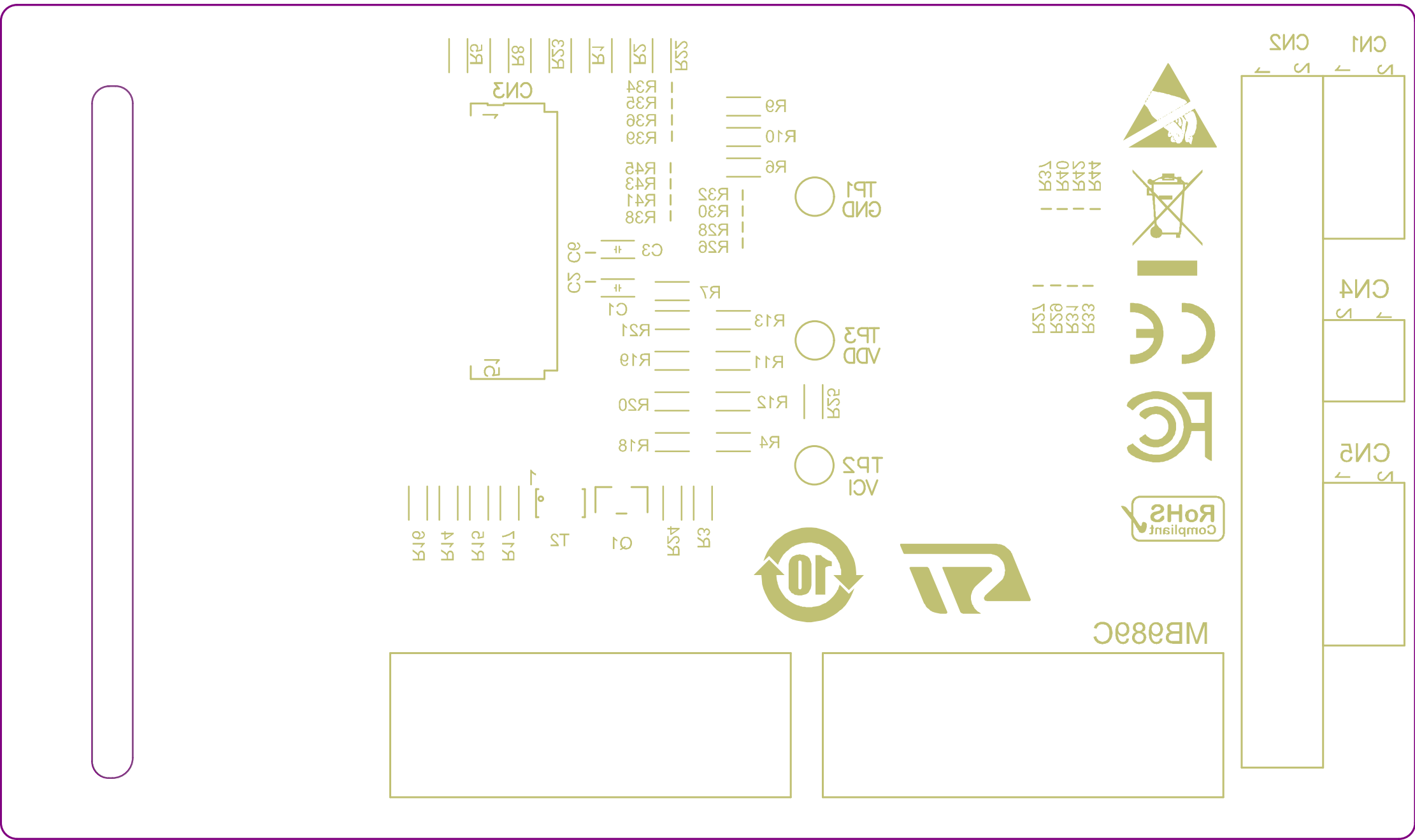


Bottom Layer
.GBL





IMPEDANCE TABLE					
LAYER	TRACE	SPACING	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP / BOTTOM	0.127	NA	50 ohm	NA	+/- 15%

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☐ NO

☐ TG-170

☒ TG-150

☐ TG-140

☐ WHITE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

☒ BLUE

☐ BLACK

☐ IMMERSION TIN

☐ GOLDEN FINGER

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	TopOverlay				/ / / / / / / / / /
2	TopSolder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		/ / / / / / / / / /
4	Dielectric1	FR-4	1,530mm	4,8	/ / / / / / / / / /
5	Bottom Layer	Copper	0,035mm		/ / / / / / / / / /
6	BottomSolder	Solder Resist	0,010mm	3,5	/ / / / / / / / / /
7	BottomOverlay				/ / / / / / / / / /

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.127 mm
GAPS : 0.127 mm

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via/Pad	Pad Shape	Hole Length	Routed Path Length
○	2	3,500mm (137,80mil)	NPTH	Top Layer - Bottom Layer	Pad	Rounded	-	-
✱	4	1,200mm (47,24mil)	NPTH	Top Layer - Bottom Layer	Pad	Rounded	-	-
▽	57	1,000mm (39,37mil)	PTH	Top Layer - Bottom Layer	Pad	Rounded	-	-
◇	143	0,203mm (8,00mil)	PTH	Top Layer - Bottom Layer	Via	Rounded	-	-
	206 Total							